

Abstract

Method for Conditioning Polishing Pads for the Simultaneous Double-Side Polishing of Semiconductor Wafers

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The invention relates to a method for conditioning polishing pads (3, 4) for the simultaneous double-side polishing of semiconductor wafers in a double-side polishing device having an annular lower polishing plate (2), an annular upper
10 polishing plate (1) and a rolling device (6, 7) for carrier disks (8), the lower polishing plate (2), the upper polishing plate (1) and the rolling device (6, 7) are mounted rotatably about collinearly arranged axes (5), and the lower polishing plate (2) being covered with a first polishing pad (4) and the
15 upper polishing plate (1) is covered with a second polishing pad (3), wherein at least one conditioning tool (11) having external teeth (12) and at least one spacer (14) having external teeth (15) are set in a revolving movement about the axis (5) of the rolling device (6, 7) and simultaneously in
20 rotation on themselves by means of the rolling device (6, 7) in a working gap formed between the first and second polishing pads (3, 4), so that the at least one conditioning tool (11) generates material abrasion of at least one of the two polishing pads (3, 4) by its relative movement, the thickness
25 (d_p) of the at least one conditioning tool (11) differing from the thickness (d_s) of the at least one spacer (14).

Drawing for the Abstract: Fig. 2